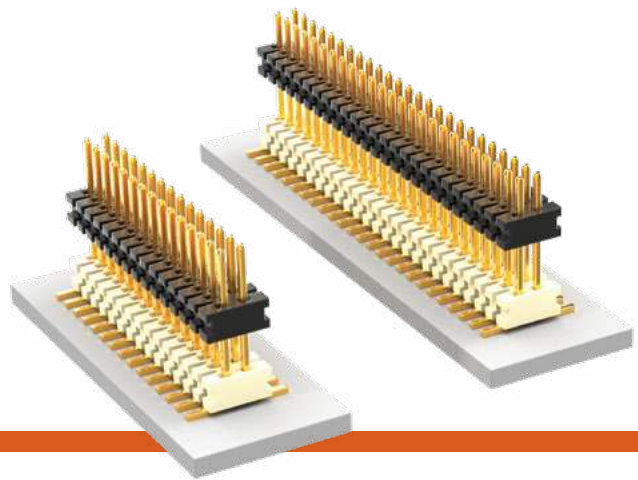


FLEX STACK

SMT MICRO BOARD HEADER

(1.00 mm) .0394" PITCH • MW SERIES



MW

Mates:
CLM, MLE

SPECIFICATIONS

Insulator Material:
Top: Black LCP
Bottom: Natural LCP
Terminal Material:
Phosphor Bronze
Plating:
Au over 50 μ " (1.27 μ m) Ni
Operating Temp Range:
-55 °C to +125 °C

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-30)
(0.15 mm) .006" max (31-50)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)

MW	-	NO. PINS PER ROW	-	03	-	PLATING OPTION	-	D	-	STACKER HEIGHT	-	POST HEIGHT	-	OPTION
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02 thru 50

-G
= 10 μ "
(0.25 μ m)
Gold

-"XXX"
= Stacker
Height
(in inches)

(2.41 mm)
.095" to
(6.22 mm)
.245"

Example:
-245
= (6.22 mm)
.245"

-"XXX"
= Post
Height
(in inches)

(1.65 mm)
.065"
minimum

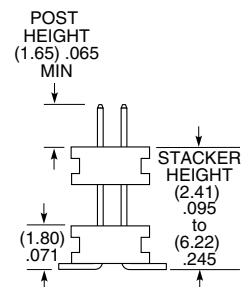
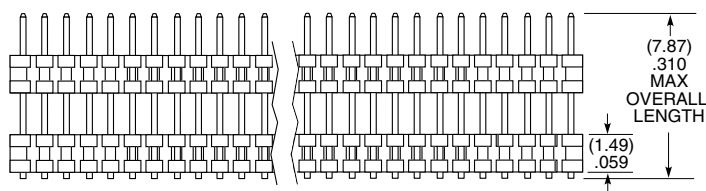
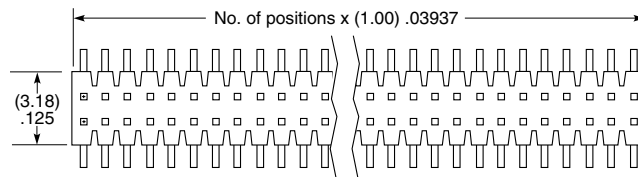
Example:
-065
= (1.65 mm)
.065"

-A
= Alignment
Pin
(5 positions
minimum)
Metal or
plastic at
Samtec's
discretion

-P
= Pick &
Place Pad
(7 positions
minimum)

-TR
= Tape & Reel

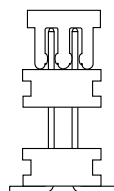
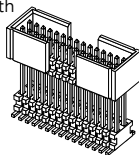
-FR
= Full Reel
Tape & Reel
(must order
maximum
quantity per
reel; contact
Samtec for
quantity
breaks)



ALSO AVAILABLE

MOQ Required

End shrouds
End shrouds with
guide posts



-P OPTION

Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

APPLICATION

EXAMPLES		
LEAD STYLE		MATED HEIGHT*
MW	CLM	
-163-065	-02	(6.35 mm) .250"
-233-065	-02	(8.13 mm) .320"

*Processing conditions will affect mated height.

